

# XChange3001

Conduction-Cooled 3U VPX-REDI XMC Carrier Card

- ▶ 3U VPX-REDI carrier card
- ▶ Conduction cooling
- ▶ Generic x8 XMC interface
- ▶ X12d+X8d+X24s I/O routing per VITA 46.9
- ▶ No drivers needed



## XChange3001

The XChange3001 is a 3U VPX-REDI carrier module supporting a single-width XMC card. It provides an easy way to integrate switched mezzanine cards into modern VPX backplanes.

The XChange3001 supports a generic x8 interface on the VPX fabric connector, allowing a variety of high-speed protocols to be used. It also supports VITA 46.9 X12d+X8d+X24s I/O routing on P2, with the option to extend XMC routing to P1.

# X-ES

Extreme Engineering Solutions

*...Always Fast*

### Extreme Engineering Solutions

9901 Silicon Prairie Parkway • Verona, WI 53593  
 Phone: 608.833.1155 • Fax: 608.827.6171  
 sales@xes-inc.com • <https://www.xes-inc.com>

**VPX**

- Generic x8 interface supporting a variety of protocols

**XMC**

- Generic x8 interface
- VITA 46.9 X12d+X8d+X24s I/O routing on P2, with option to extend routing to P1

**Physical Characteristics**

- 3U VPX form factor
- Dimensions: 100 mm x 160 mm, 10 mm stacking height

**Power Requirements**

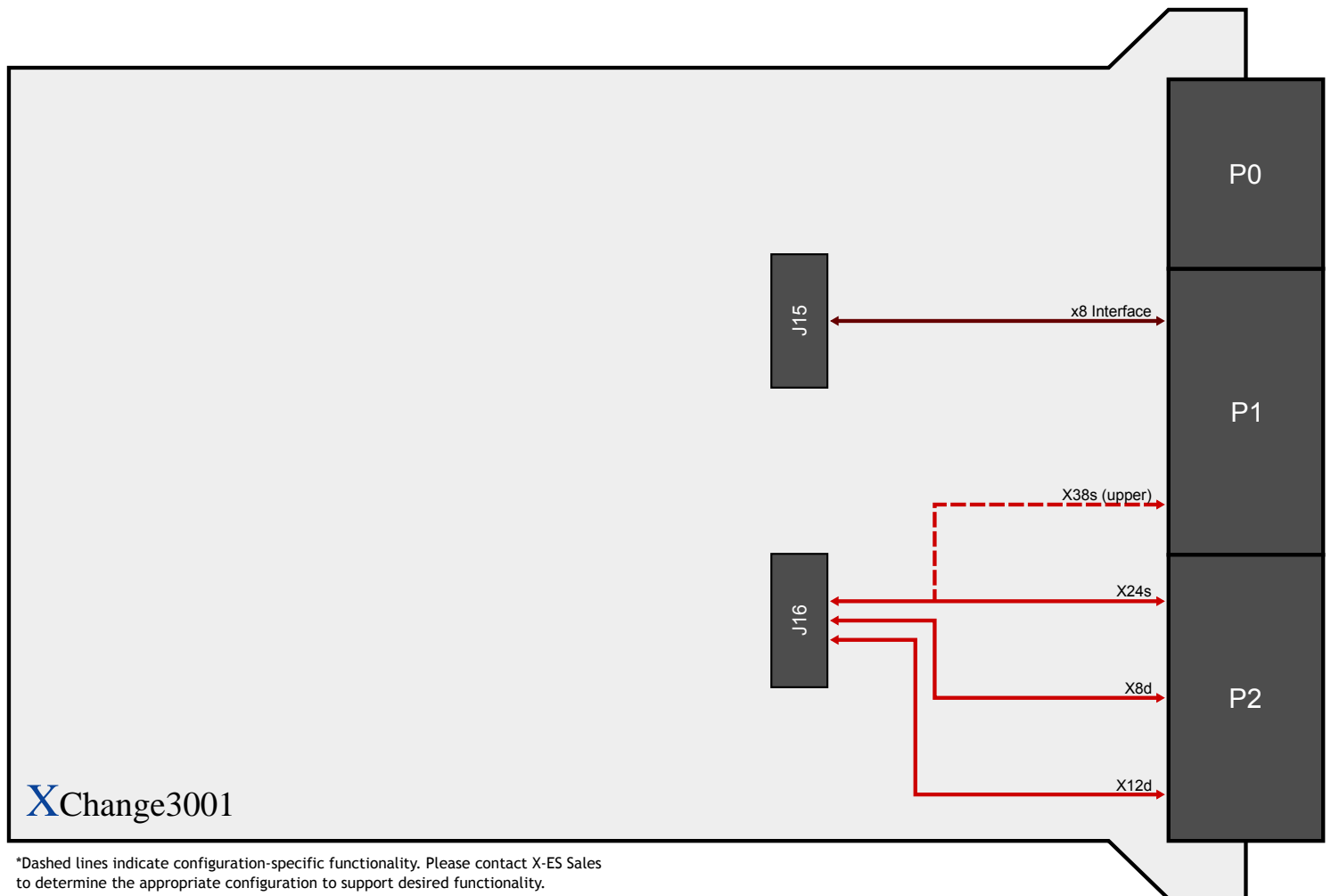
Power will vary based on configuration and usage. Please consult factory.

**Environmental Requirements**

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 5
- Conformal coating available as an ordering option

<b>Ruggedization Level</b>	<b>Level 5</b>
<b>Cooling Method</b>	Conduction-Cooled
<b>Operating Temperature</b>	-40 to +85°C (board rail surface)
<b>Storage Temperature</b>	-55 to +105°C (maximum)
<b>Vibration</b>	0.1 g <sup>2</sup> /Hz (maximum), 5 to 2000 Hz
<b>Shock</b>	40 g, 11 ms sawtooth
<b>Humidity</b>	Up to 95% non-condensing



\*Dashed lines indicate configuration-specific functionality. Please contact X-ES Sales to determine the appropriate configuration to support desired functionality.